D&LLTechnologies

EGW-3200 / EGW-5200 Spec Sheet



Access the full potential of your edgegenerated data

Intel[®] Processor-Based Intelligent Edge Gateways

The new intelligent Dell EMC Edge Gateways help companies connect OT/IT environments and extract value from their edge-generated data with no interruptions to their infrastructure. The EGW-3200 and EGW-5200 enable customers to collect, consolidate, and perform lightweight analyses on the vast data generated from multiple edge devices. With a rugged and fanless design, the edge gateways are compact and robust enough to endure 24/7/365 operations. They are engineered as modular designs with certified and qualified peripherals. These long-life platforms provide OEM-ready and customizable options to best fit a range of industrial needs. They are purpose-built to power real-time insights that will lead to better efficiency, lower costs, and greater performance for your business.

Actionable insights where you need them

Dell EMC Edge Gateways bridge your legacy systems and modern sensors to the internet, enabling you to faster collect and process data at the edge, reducing response time and saving bandwidth. The latest Intel SoC processors provide you with the speed and power to run intensive workloads, especially when combined with applications that enhance automated data curation and analytics capabilities, helping you to extract actionable insights that will be valuable to your business. The new edge gateways enable you to process what is important locally, where and when speed matters.

Uninterrupted performance anywhere, anytime

Ensure that your operations and productivity keep running to boost real-time performance. Engineered with an industrialgrade form factor, these gateways can be used in multiple circumstances without compromising on energy consumption. They offer several features for reducing power usage, helping you save on your operations.

Features

- Intel Atom[®] and Core[™] processors
- SO-DIMM for DDR4 memory
- Rich I/O: DP++, DVI, VGA, GbE, COM, USB, DI/O
- Security: TPM2.0
- Rich storage: 2.5" SATA / M.2
- Embedded expansion: Mini PCIe/uFM/M.2/USIM
- (EGW-3200) Optional sensor suite: accelerometer, humidity, pressure, temperature
- (EGW-3200) Dual DC input options: DC terminal block or PoE PD
- WiFi/Bluetooth

Software Support

- Win10 LTSC 2019
- Linux Ubuntu 20.04 LTS

Optional Accessories – Qualified and Certified

- Expansion modules (mPCle or uFM) for Isolated COM (RS-232 or RS-422/485), GbE with PoE, GbE LAN, Canbus
- 4G and 5G modules
- AC-to-DC adapter

Features	EGW-3200	EGW-5200	
Processor	Intel Atom [®] x6425RE	Intel [®] Core™ i7-9700 / i5-9500 / i3-9100 TE	
TDP	12 W	35 W	
# of Cores	4	8/6/4	
Base Freq.	1.9 GHz	1.8 GHz / 2.2 GHz / 2.2 GHz	
Max. Turbo Freq.	_	3.8 GHz / 3.6 GHz / 3.2 GHz	
PCH	Elkhart Lake SoC	C246	
Memory	SO-DIMM for DDR4 3200 MHz, up to 32 GB	2x DDR4 SO-DIMMs, up to 64 GB	
I/O interfaces			
Display	2x DP++	2x DP++, DVI-D, VGA	
Ethernet	1x 2.5 GbE, 1x GbE (1 GHz)	3x Intel GbE: 2x i210 + i219LM PHY, iAMT supported on i5 and i7 CPUs	
Serial Ports	COM1/2: RS-232/422/485	COM1/2: RS-232/422/485, COM3/4: RS-232	
DI/O	6-ch DI and 6-ch DO	8-ch DI and 8-ch DO	
USB	4x external USB 3.1 Gen1	6x external USB ports (2x USB 3.1 Gen2 + 1x USB 3.1 Gen1 + 3x USB 2.0), 1x internal USB 2.0 port	
Audio	Line-out, mic-in	Line-out, mic-in	
Mini PCle	1x full size 3050	1x full size (USB 2.0+PCIe), used for WiFi by default	
	Socket 1: for module with A/A+E key Socket 2: for module with B/B+M key Socket 3: for module with M key	1x socket 2, key B+M or B 1x 2280/3042 (USB 3.1 + SATA 6 Gb/s + 2x PCIe)	
Sensor Suite	Accelerometer, humidity, pressure, temperature		
Wafer	1x (signal: 2x I2C, 1x USB 2.0)		
USIM	2x nanoSIM slot	2x nanoSIM slot	
Security			
ТРМ	TPM2.0	TPM2.0	
Storage			
Disk	1x M.2 SSD on M.2 Socket 3	2x internal 2.5" SATA	
Physical			
Dimensions	162 mm (W) x 108 mm (D) x 60 mm (H)	211 mm (W) x 240 mm (D) x 86 mm (H)	
Weight	Net: 1.2 kg; gross: 1.7 kg	4.7 kg	
Mounting	Wall mount / DIN rail supported	Desktop, operational: wall mount	
Power supply			
DC Input	9–36 V (±10% tolerance)	12–24 V (±10% tolerance)	
AC Input	Optional: 120 W, 60 W (for PoE) AC-to-DC adapter	Optional: 180 W, 60 W (for PoE) AC-to-DC adapter	
Environmental			
Operating temperature	–20°C to 60°C (with airflow 0.6 m/s)	0°C to 60°C (with airflow 0.6 m/s)	
Storage temperature	-40°C to 85°C (excluding storage devices)	-40°C to 85°C (excluding storage devices)	
	Operational (maximum, unpressurized): –15.20 m to 5,000 m Note: The maximum temperature is derated 1ºC/305 m above sea level altitude		
Humidity		~95% at 40°C (non-condensing)	
Tarmany	~95% at 40°C (non-condensing)		
-	~95% at 40°C (non-condensing) MIL-STD-810G METHOD 514.6 category 4 - common	carrier (US highway truck vibration exposure)	
Vibration Shock			
Vibration Shock	MIL-STD-810G METHOD 514.6 category 4 - common 1. IEC 60068-2-27, half-sine pulse test parameters		
Vibration Shock IP rating	 MIL-STD-810G METHOD 514.6 category 4 - common 1. IEC 60068-2-27, half-sine pulse test parameters 2. 20G, MIL-STD-810G METHOD 516.6 Table 516.6 	6-II, sawtooth pulse test parameters	